

Surface Mount Thin-Film Filters

50Ω DC to 40 GHz

The Big Deal

- Low passband insertion loss
- High rejection
- Good power handling
- Temperature stability -55°C to 125°C
- High repeatability
- RoHS complaint
- Small size



Product Overview

Mini-Circuits' *Surface Mount Thin-Film filters* offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance.

Low pass, high pass and bandpass surface mount thin-film designs can be realized with this technology. Using thin-film manufacturing, we can guarantee repeatability on large batches of filters. Thin-film filters are small in size with high-quality, precise machining for applications where size is critical.

Key Features

Feature	Advantages
Low insertion loss	High Q material and sputtering process results in lower insertion loss, better SNR is obtained.
Fast roll-off (steeper skirts)	High selectivity results in better adjacent channel rejection and dynamic range
Wider stopband	Wide spur-free stopband results in better adjacent channel rejection and dynamic range
Temperature stability	Very minimal change in electrical performance across temperature makes these filters suitable for a wide range of operating conditions.
Small Size	Various design techniques are employed to realize small size.

Notes

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B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp



Surface mount Thin Film Bandpass Filter

50Ω 6750 to 7500 MHz

ABF-7G+



Generic photo used for illustration purposes only

CASE STYLE: UC2731

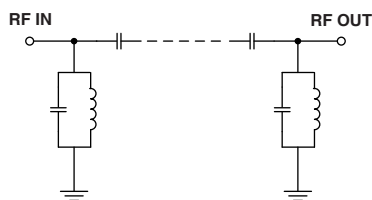
Features

- Low passband insertion loss of 1.3dB typical
- High rejection of 60dB typical
- Good Return loss of 15dB typical
- Small size

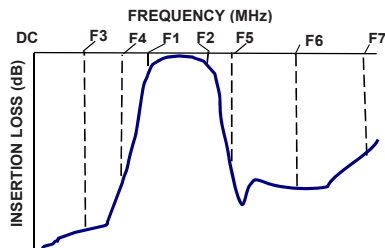
Applications

- 5G
- Wireless communication systems
- Satellite communication
- Military and Defense
- Test and measurement

Functional Schematic



Typical Frequency Response



Electrical Specifications⁽¹⁾ at 25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Unit
Pass Band	Insertion Loss	F1-F2	6750 - 7500	—	1.3	2.5	dB
	Return Loss	F1-F2	6750 - 7500	—	15	—	dB
Stop Band, Lower	Insertion Loss	DC-F3	DC - 5250	40	55	—	dB
		F3-F4	5250 - 5800	20	35	—	dB
Stop Band, Upper	Insertion Loss	F5-F6	8350 - 9000	20	45	—	dB
		F6-F7	9000 - 14000	40	50	—	dB

1. Measured on Mini-Circuits Characterization Test Board TB-ABF-7G+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.

Maximum Ratings

Operating Temperature	-55°C to 125°C
Storage Temperature	-55°C to 125°C
RF Power Input	1W Max. @ 25°C

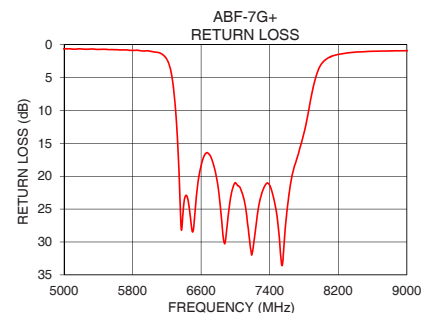
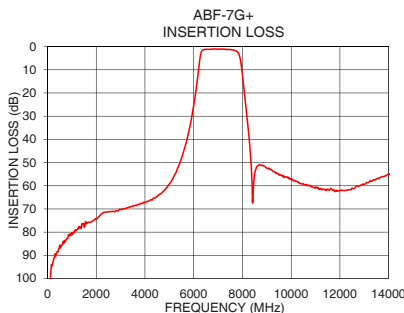
Permanent damage may occur if any of these limits are exceeded.

Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
10	119.18	0.08
1010	81.13	0.34
3460	69.03	0.33
5250	54.70	0.69
5800	36.59	0.87
5920	30.43	0.96
6075	20.32	1.14
6290	3.12	8.12
6500	1.18	28.48
6750	1.12	18.48
7000	1.06	20.99
7250	1.10	26.55
7500	1.29	27.69
7850	3.15	10.32
8080	19.95	2.03
8180	29.75	1.54
8350	49.47	1.19
9000	52.47	0.92
12000	62.03	0.90
14000	55.20	1.04

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



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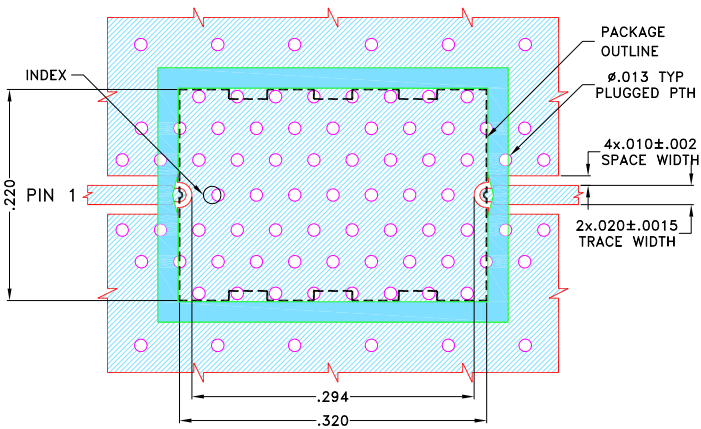
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Pad Connections

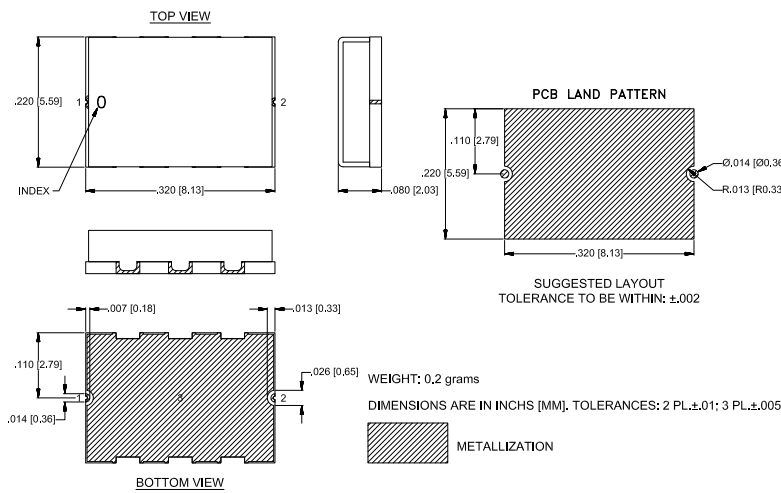
RF IN	1
RF OUT	2
GROUND	3

Demo Board MCL P/N: TB-ABF-7G+
Suggested PCB Layout (PL-652)



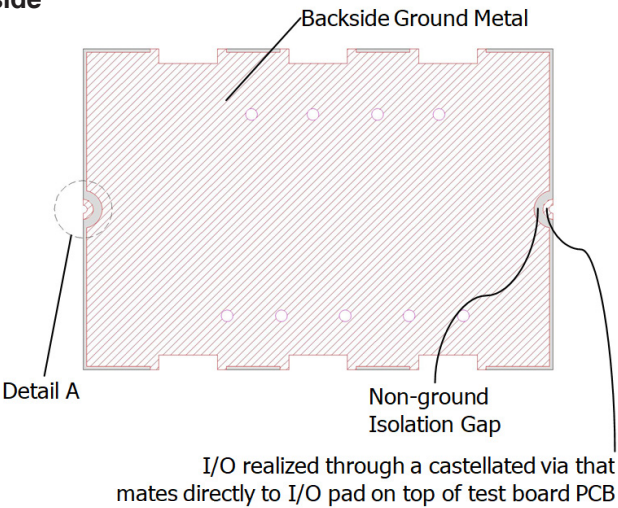
- NOTES:
1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (R04350B) WITH DIELECTRIC THICKNESS .010±.0010. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
- DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

Outline Drawing



Recommendations of PCB pattern at customer board

Filter Back side



Notes

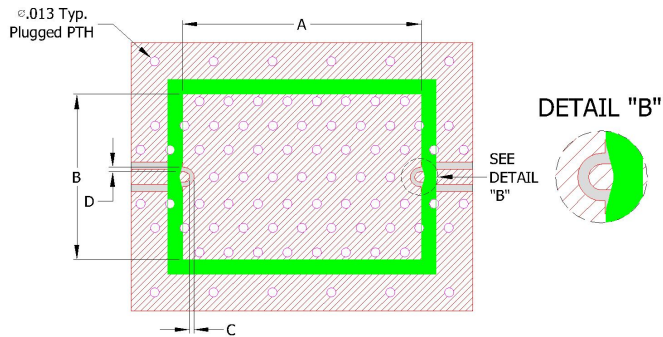
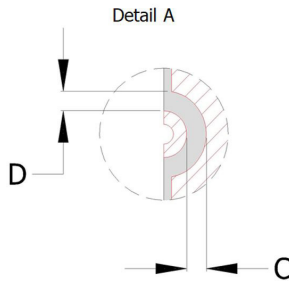
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PCB Pattern Recommendations

Filter RF I/O Detail
(Filter Back Side)

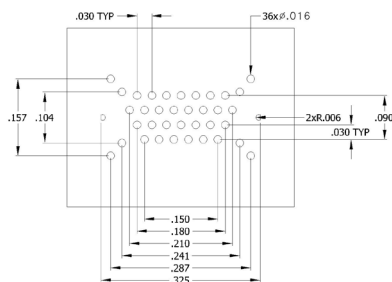


- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
- 5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

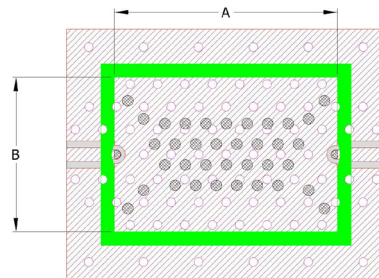
Comments on component handling and solder attach

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.

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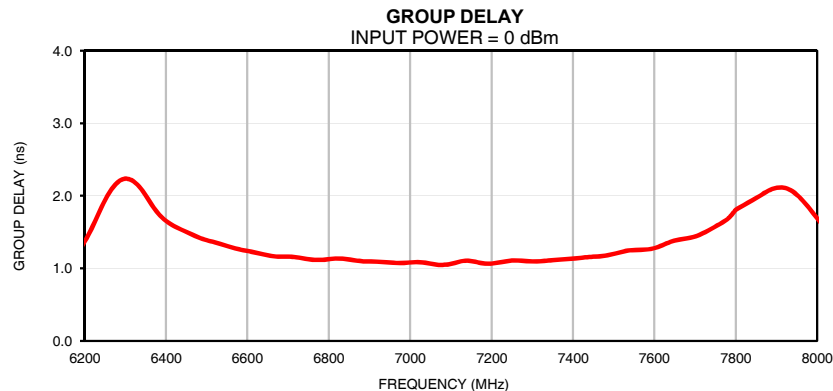
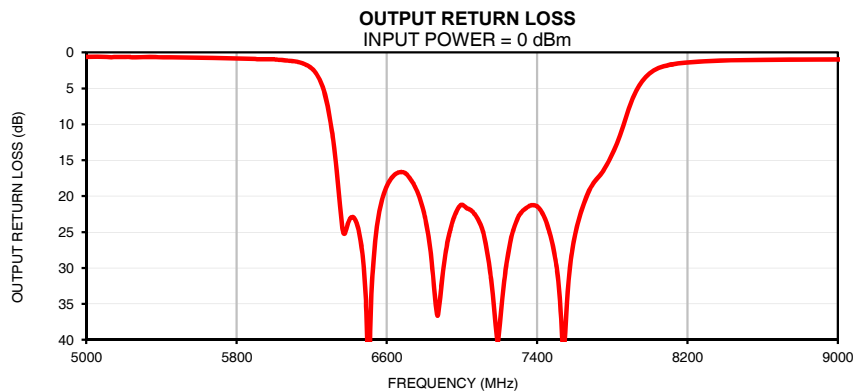
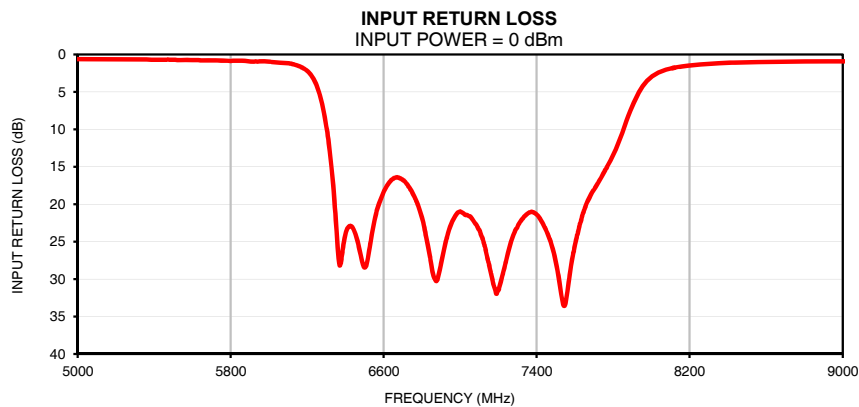


Typical Performance Data

FREQ.	Insertion Loss	Input Return Loss	Output Return Loss
(MHz)	(dB)	(dB)	(dB)
10	119.18	0.08	0.09
60	102.34	0.11	0.11
110	101.24	0.06	0.07
360	89.33	0.23	0.22
610	85.38	0.29	0.28
810	82.63	0.34	0.32
1010	81.13	0.34	0.32
1260	78.57	0.35	0.33
1510	77.86	0.32	0.30
1760	75.72	0.37	0.35
2010	74.35	0.31	0.30
3010	70.21	0.26	0.23
3560	68.56	0.36	0.33
4010	67.32	0.39	0.36
4235	66.10	0.42	0.40
4260	66.01	0.43	0.40
4510	64.55	0.50	0.49
4760	62.26	0.58	0.58
5010	59.03	0.63	0.62
5250	54.70	0.69	0.66
5800	36.59	0.87	0.85
5920	30.43	0.96	0.93
6075	20.32	1.14	1.14
6195	10.33	2.11	2.10
6290	3.12	8.12	8.13
6500	1.18	28.48	47.37
6600	1.17	18.35	18.58
6700	1.15	16.75	16.84
6800	1.06	21.80	22.61
6900	1.05	27.94	30.32
7000	1.06	20.99	21.20
7100	1.08	23.49	24.05
7200	1.12	31.49	38.31
7300	1.17	22.99	22.87
7400	1.23	21.36	21.44
7500	1.29	27.69	29.27
7850	3.15	10.32	10.79
7980	10.39	3.44	3.33
8080	19.95	2.03	1.89
8180	29.75	1.54	1.44
8350	49.47	1.19	1.16
8500	55.07	1.07	1.06
8750	51.14	0.96	0.98
9000	52.47	0.92	0.97
9300	53.92	0.86	0.92
9600	55.39	0.85	0.92
9900	56.82	0.86	0.92
10200	58.13	0.85	0.90
10500	59.21	0.84	0.85
10800	60.24	0.83	0.83
11100	60.81	0.84	0.83
11400	61.74	0.85	0.84
11700	61.83	0.88	0.86
12000	62.03	0.90	0.88
12300	61.92	0.93	0.90
12600	61.12	0.96	0.94
12900	59.70	0.98	0.98
13200	58.39	1.00	1.00
13500	56.96	0.99	1.03
14000	55.20	1.04	1.06

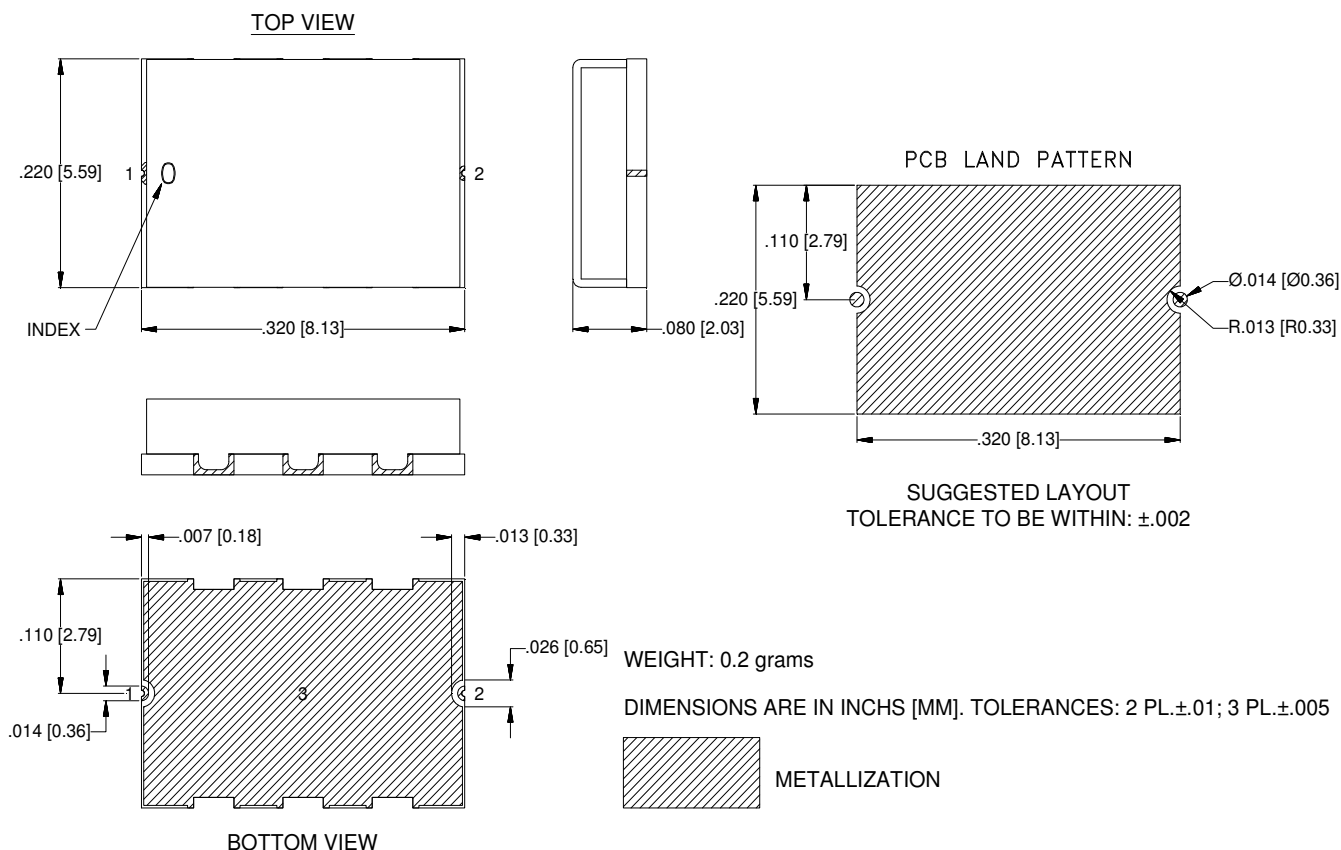
FREQ.	Group Delay
(MHz)	(ns)
6500	1.39
6515	1.37
6530	1.34
6545	1.32
6560	1.29
6575	1.27
6590	1.25
6605	1.23
6620	1.22
6635	1.20
6650	1.18
6665	1.17
6680	1.16
6700	1.16
6715	1.16
6730	1.15
6745	1.13
6760	1.12
6775	1.11
6800	1.13
6815	1.13
6830	1.13
6845	1.13
6860	1.11
6875	1.10
6900	1.09
6915	1.09
6930	1.09
6945	1.08
6960	1.08
6975	1.07
7000	1.08
7015	1.09
7030	1.08
7045	1.07
7060	1.05
7075	1.05
7100	1.06
7115	1.08
7130	1.10
7145	1.10
7160	1.09
7175	1.07
7200	1.06
7215	1.08
7230	1.09
7245	1.10
7260	1.11
7275	1.10
7300	1.09
7315	1.10
7330	1.10
7345	1.11
7360	1.12
7375	1.12
7400	1.13
7415	1.14
7430	1.15
7450	1.16
7500	1.20

Typical Performance Curves



Outline Dimensions

UC2731



Notes:

1. Case material: Gold over Nickel over Annealed Stainless Steel.
2. Base: Ceramic
3. Termination finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Gold over Nickel plate. All models, (+) suffix.



P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



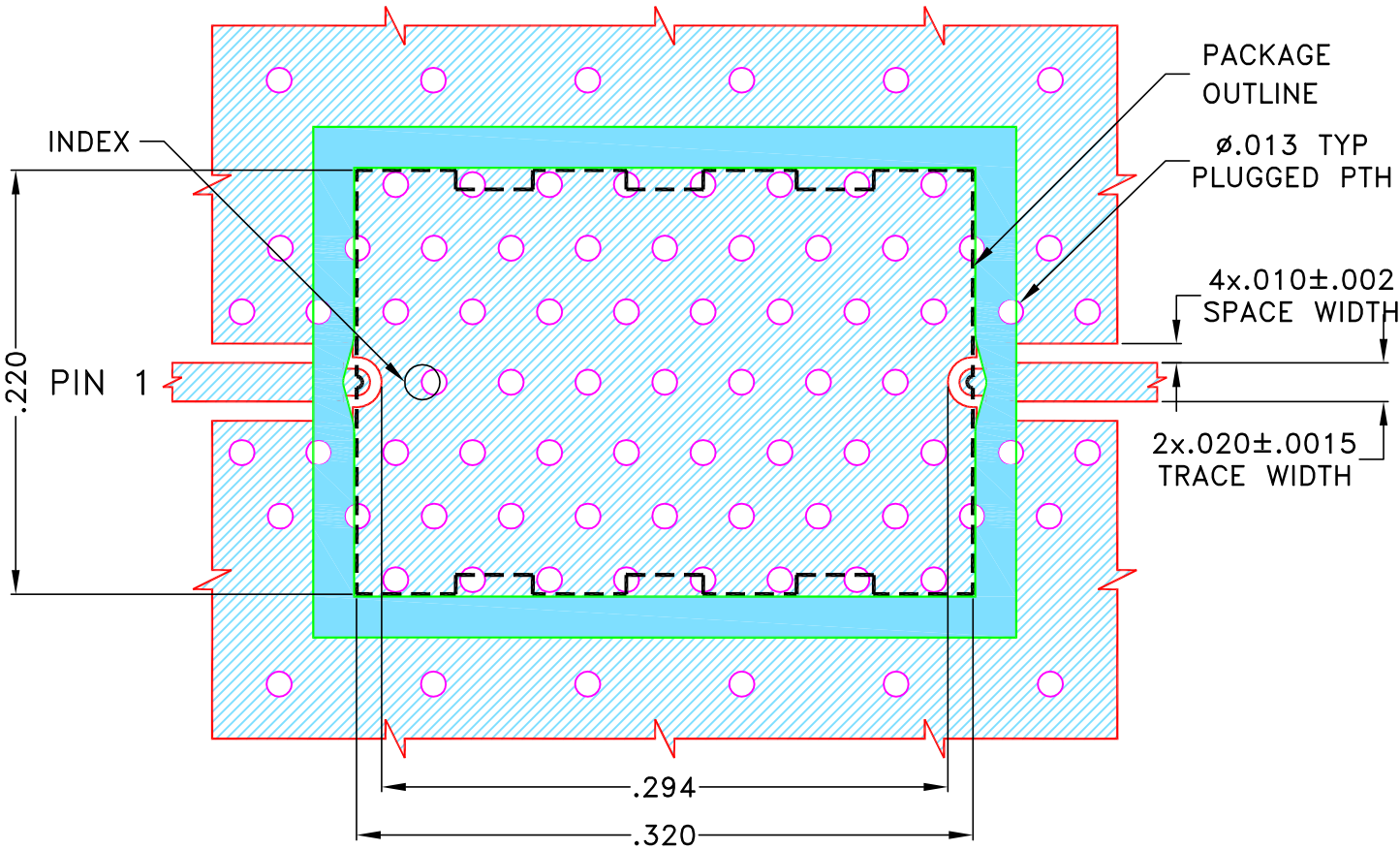
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RF/IF MICROWAVE COMPONENTS


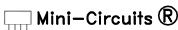


THIRD ANGLE PROJECTION		REVISIONS				
	REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
	OR	ECO-007104	NEW RELEASE	MAR 21	DDR	VC
	A	ECO-010633	UPDATED AS PER CURRENT TEST BOARD	NOV 21	DDR	VC

SUGGESTED MOUNTING CONFIGURATION
FOR UC2731 CASE STYLE

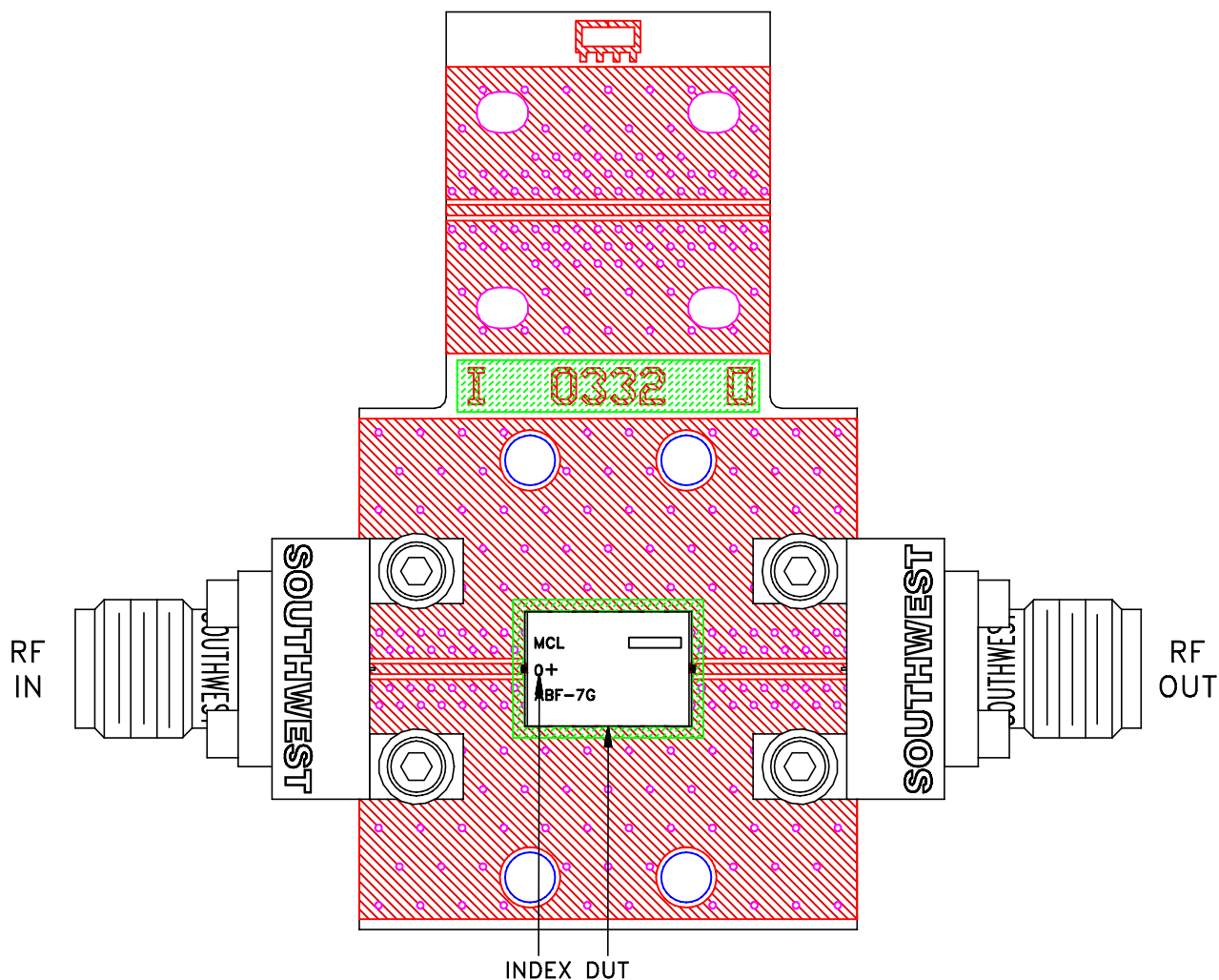


- NOTES:
- COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (R04350B) WITH DIELECTRIC THICKNESS .010±.0010. COPPER: 1/2 Oz. EACH SIDE.
FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
 - BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
-  DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
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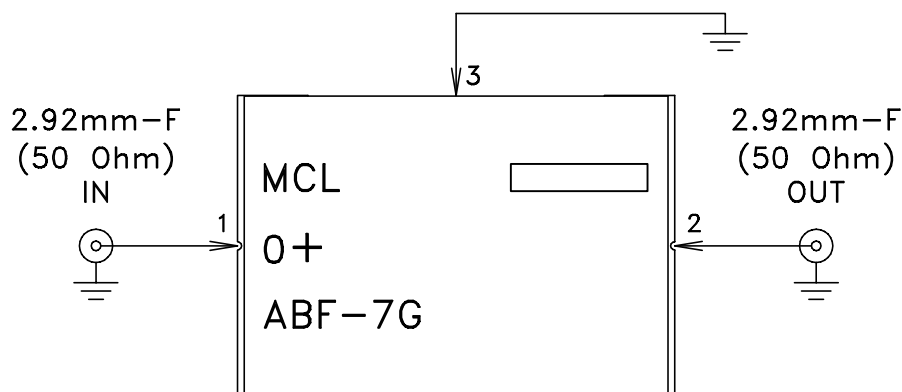
UNLESS OTHERWISE SPECIFIED		INITIALS	DATE	 Mini-Circuits® 13 Neptune Avenue Brooklyn NY 11235		
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ±	DRAWN	DDR	29 MAR 21			
	CHECKED	RR	29 MAR 21			
	APPROVED	NN	29 MAR 21			
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		SIZE	CODE IDENT	DRAWING NO:	REV:	
		A	15542	98-PL-652	A	
		FILE:	98-PL-652	SCALE:	10:1	SHEET: 1 OF 1
ASHEETA1.DWG REV:A DATE:01/12/95						

Evaluation Board and Circuit

TB-ABF-7G+




Schematic diagram



Notes:

1. PCB Material: ROGERS (R04350B) OR Equivalent, Dielectric Constant= 3.48 ± 0.05
Dielectric Thickness: $.010 \pm .001$
2. 50 Ohm 2.92mm Female Connectors.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Thermal Shock	-55° to 125°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, Except +125°C